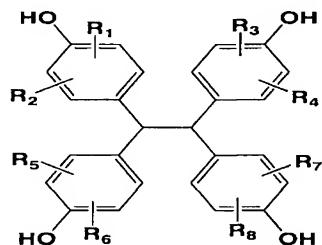


CLAIMS

1. A photosensitive resin composition containing a resin (A) soluble in an aqueous alkaline solution, a crosslinking agent (B), a photopolymerization initiator (C), and a curing agent (D), wherein the curing agent (D) is an epoxy compound obtained by glycidylating a compound containing not less than 80% of a tetraphenylethane derivative represented by formula (1):



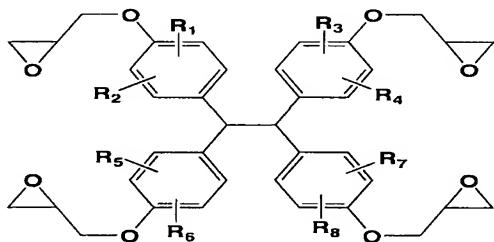
(1)

[wherein R₁ to R₈ each independently represents a hydrogen atom, a C₁ to C₄ alkyl group, or a halogen atom].

2. The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), is a compound obtained by glycidylating a tetraphenylethane derivative represented by formula (1) wherein each R₁ to R₈ is

a hydrogen atom, and the compound has an epoxy equivalent of 120 to 200 g/equivalent.

3. The photosensitive resin composition according to Claim 1, wherein the epoxy compound, which is the curing agent (D), includes a compound represented by formula (2):



(2)

[wherein R₁ to R₈ each independently represents a hydrogen atom, a C₁ to C₄ alkyl group, or a halogen atom] and the content of the compound in the curing agent (D) is not less than 60 mole percent.

4. The photosensitive resin composition according to any one of Claims 1 to 3, wherein the curing agent (D) has a softening point or melting point of not less than 80°C.

5. The photosensitive resin composition according to any one

of Claims 1 to 3, wherein the curing agent (D) has a light transmittance at 400 nm of not less than 10% in a 1 weight percent methyl ethyl ketone solution.

6. The photosensitive resin composition according to any one of Claims 1 to 5, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (a) having two or more epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, and a polybasic acid anhydride (c).

7. The photosensitive resin composition according to any one of Claims 1 to 5, wherein the resin (A) soluble in the aqueous alkaline solution is a reaction product between an epoxy carboxylate compound obtained by reaction of an epoxy compound (d) having two epoxy groups per molecule with a monocarboxylic acid (b) having an ethylenic unsaturated group per molecule, a diisocyanate compound (e), a carboxylic acid (f) having two hydroxyl groups per molecule, and, as an optional component, a diol compound (g).

8. A cured product of the photosensitive resin composition according to any one of Claims 1 to 7.

9. A substrate comprising a layer composed of the cured

product according to Claim 8.

10. An article comprising the substrate according to Claim 9.